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April 2016

FGA30S120P

1300 V, 30 A Shorted-anode IGBT

Features

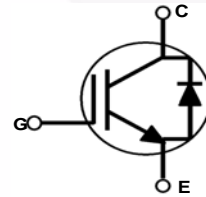
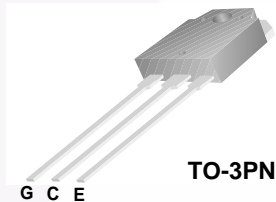
- High Speed Switching
- Low Saturation Voltage: $V_{CE(sat)} = 1.75 \text{ V @ } I_C = 30 \text{ A}$
- High Input Impedance
- RoHS Compliant

Applications

- Induction Heating, Microwave Oven

General Description

Using advanced field stop trench and shorted-anode technology, Fairchild's shorted-anode Trench IGBTs offer superior conduction and switching performances for soft switching applications. The device can operate in parallel configuration with exceptional avalanche capability. This device is designed for induction heating and microwave oven.



Absolute Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Description	Ratings	Unit
V_{CES}	Collector to Emitter Voltage	1300	V
V_{GES}	Gate to Emitter Voltage	± 25	V
I_C	Collector Current @ $T_C = 25^\circ\text{C}$	60	A
	Collector Current @ $T_C = 100^\circ\text{C}$	30	A
$I_{CM(1)}$	Pulsed Collector Current	150	A
I_F	Diode Continuous Forward Current @ $T_C = 25^\circ\text{C}$	60	A
I_F	Diode Continuous Forward Current @ $T_C = 100^\circ\text{C}$	30	A
P_D	Maximum Power Dissipation @ $T_C = 25^\circ\text{C}$	348	W
	Maximum Power Dissipation @ $T_C = 100^\circ\text{C}$	174	W
T_J	Operating Junction Temperature	-55 to +175	$^\circ\text{C}$
T_{stg}	Storage Temperature Range	-55 to +175	$^\circ\text{C}$
T_L	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds	300	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JC}(\text{IGBT})$	Thermal Resistance, Junction to Case	--	0.43	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	--	40	$^\circ\text{C/W}$

Notes:
1: Limited by T_{Jmax}

FGA30S120P — 1300 V, 30 A Shorted-anode IGBT

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FGA30S120P	FGA30S120P	TO-3P	Tube	N/A	N/A	30

Electrical Characteristics of the IGBT T_C = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
BV_{CES}	Collector to Emitter Breakdown Voltage	$V_{GE} = 0\text{ V}, I_C = 1\text{ mA}$	1300	-	-	V
$\Delta BV_{CES} / \Delta T_J$	Temperature Coefficient of Breakdown Voltage	$V_{GE} = 0\text{ V}, I_C = 1\text{ mA}$	-	1.3	-	V/°C
I_{CES}	Collector Cut-Off Current	$V_{CE} = 1300, V_{GE} = 0\text{ V}$	-	-	1	mA
I_{GES}	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0\text{ V}$	-	-	±500	nA
On Characteristics						
$V_{GE(th)}$	G-E Threshold Voltage	$I_C = 30\text{ mA}, V_{CE} = V_{GE}$	4.5	6.0	7.5	V
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage	$I_C = 30\text{ A}, V_{GE} = 15\text{ V}$ $T_C = 25^\circ\text{C}$	-	1.75	2.3	V
		$I_C = 30\text{ A}, V_{GE} = 15\text{ V},$ $T_C = 125^\circ\text{C}$	-	1.85	-	V
		$I_C = 30\text{ A}, V_{GE} = 15\text{ V},$ $T_C = 175^\circ\text{C}$	-	1.9	-	V
V_{FM}	Diode Forward Voltage	$I_F = 30\text{ A}, T_C = 25^\circ\text{C}$	-	1.7	2.2	V
		$I_F = 30\text{ A}, T_C = 175^\circ\text{C}$	-	2.1	-	V
Dynamic Characteristics						
C_{ies}	Input Capacitance	$V_{CE} = 30\text{ V}, V_{GE} = 0\text{ V},$ $f = 1\text{ MHz}$	-	3345	-	pF
C_{oes}	Output Capacitance		-	75	-	pF
C_{res}	Reverse Transfer Capacitance		-	60	-	pF
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	$V_{CC} = 600\text{ V}, I_C = 30\text{ A},$ $R_G = 10\Omega, V_{GE} = 15\text{ V},$ Resistive Load, $T_C = 25^\circ\text{C}$	-	39	-	ns
t_r	Rise Time		-	360	-	ns
$t_{d(off)}$	Turn-Off Delay Time		-	620	-	ns
t_f	Fall Time		-	160	-	ns
E_{on}	Turn-On Switching Loss		-	1.3	-	mJ
E_{off}	Turn-Off Switching Loss		-	1.22	-	mJ
E_{ts}	Total Switching Loss		-	2.52	-	mJ
$t_{d(on)}$	Turn-On Delay Time	$V_{CC} = 600\text{ V}, I_C = 30\text{ A},$ $R_G = 10\Omega, V_{GE} = 15\text{ V},$ Resistive Load, $T_C = 175^\circ\text{C}$	-	38	-	ns
t_r	Rise Time		-	375	-	ns
$t_{d(off)}$	Turn-Off Delay Time		-	635	-	ns
t_f	Fall Time		-	270	-	ns
E_{on}	Turn-On Switching Loss		-	1.59	-	mJ
E_{off}	Turn-Off Switching Loss		-	1.78	-	mJ
E_{ts}	Total Switching Loss		-	3.37	-	mJ
Q_g	Total Gate Charge	$V_{CE} = 600\text{ V}, I_C = 30\text{ A},$ $V_{GE} = 15\text{ V}$	-	78	-	nC
Q_{ge}	Gate to Emitter Charge		-	4.2	-	nC
Q_{gc}	Gate to Collector Charge		-	33.3	-	nC

Typical Performance Characteristics

Figure 1. Typical Output Characteristics

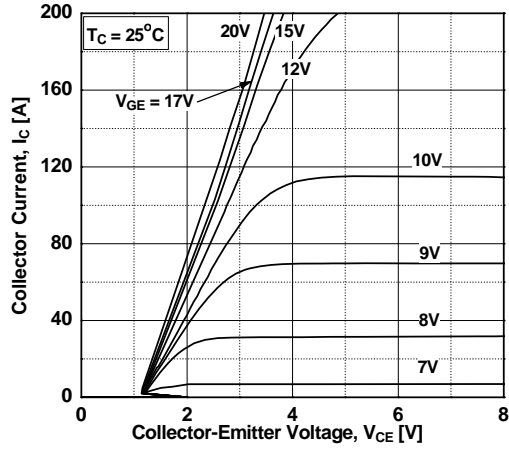


Figure 2. Typical Output Characteristics

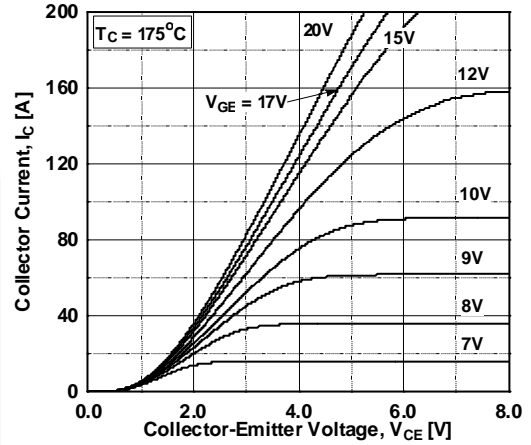


Figure 3. Typical Saturation Voltage Characteristics

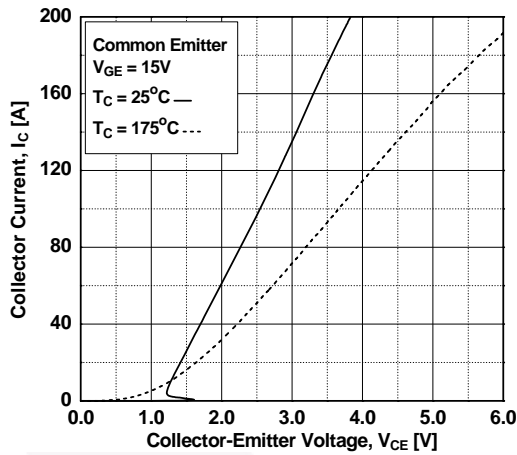


Figure 4. Transfer Characteristics

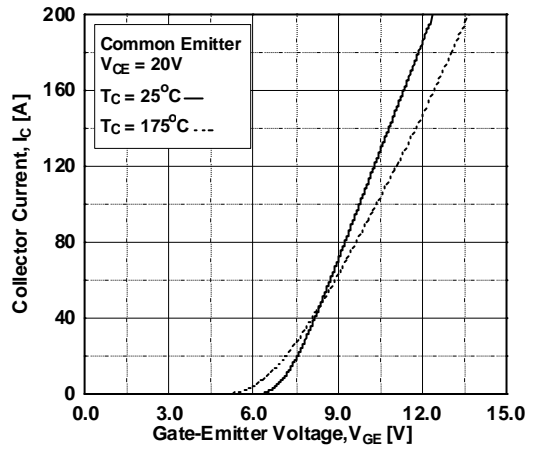


Figure 5. Saturation Voltage vs. Case Temperature at Variant Current Level

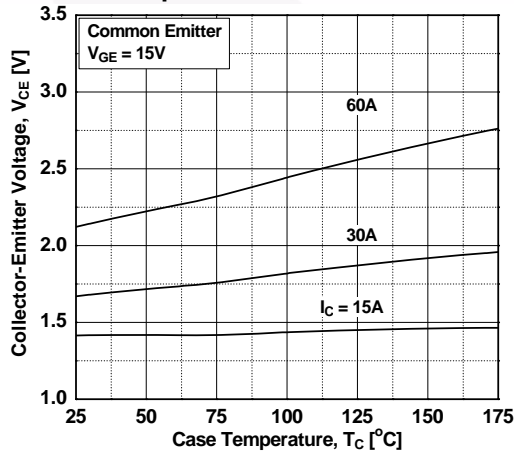
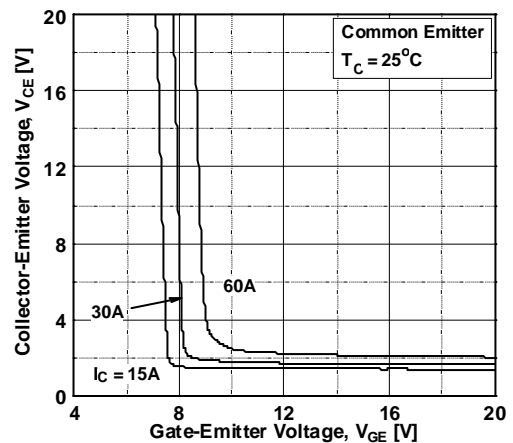


Figure 6. Saturation Voltage vs. Vge



Typical Performance Characteristics

Figure 7. Saturation Voltage vs. V_{GE}

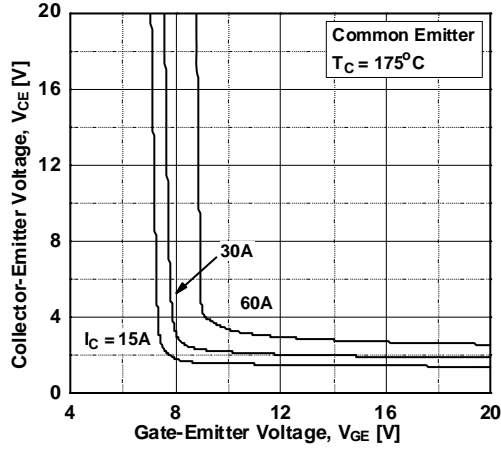


Figure 8. Capacitance Characteristics

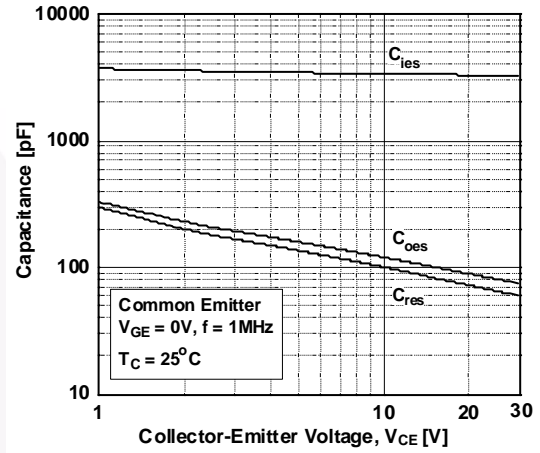


Figure 9. Gate Charge Characteristics

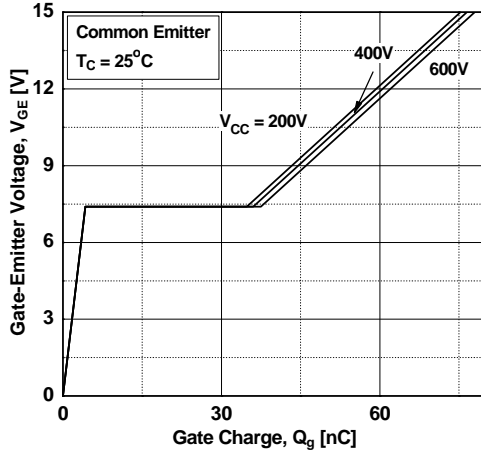


Figure 10. SOA Characteristics

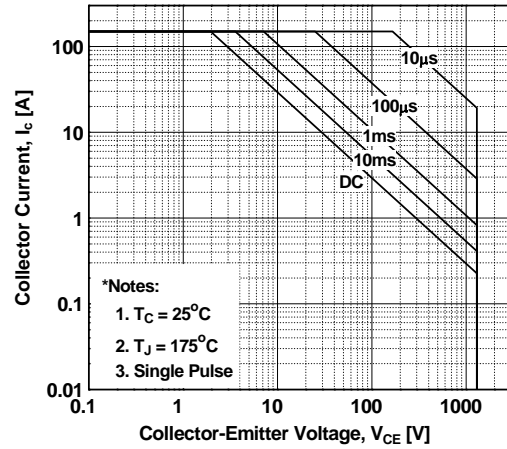


Figure 11. Turn-On Characteristics vs Gate Resistance

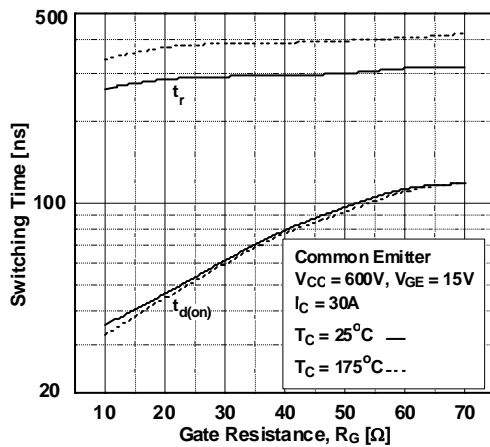
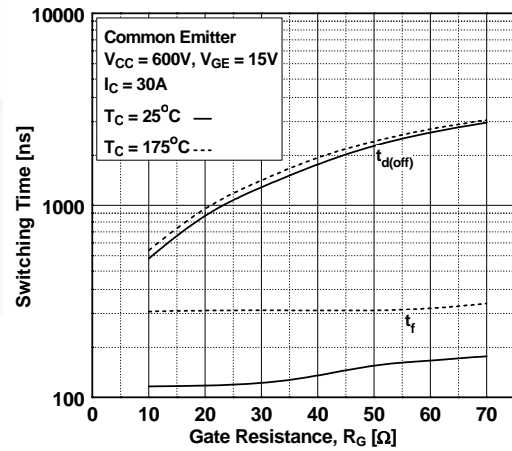


Figure 12. Turn-off Characteristics vs. Gate Resistance



Typical Performance Characteristics

Figure 13. Turn-on Characteristics VS. Collector Current

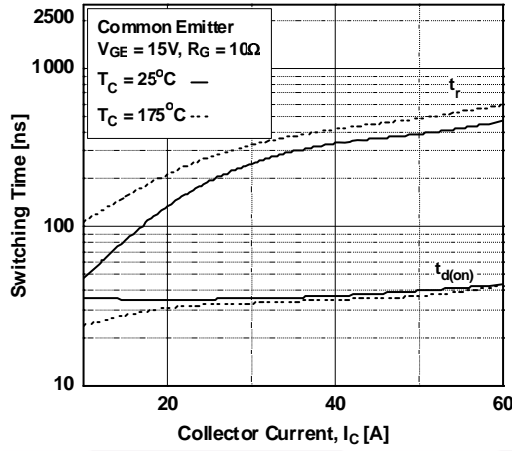


Figure 14. Turn-off Characteristics VS. Collector Current

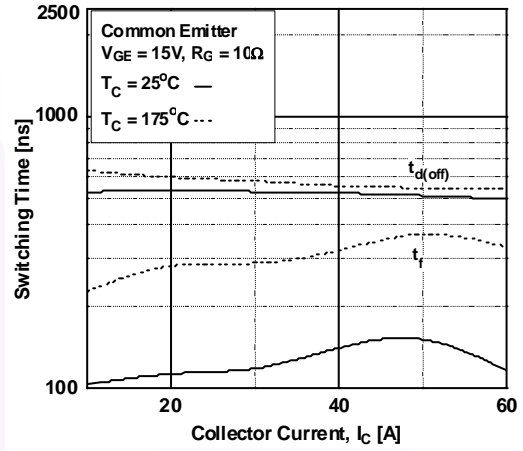


Figure 15. Switching Loss VS. Gate Resistance

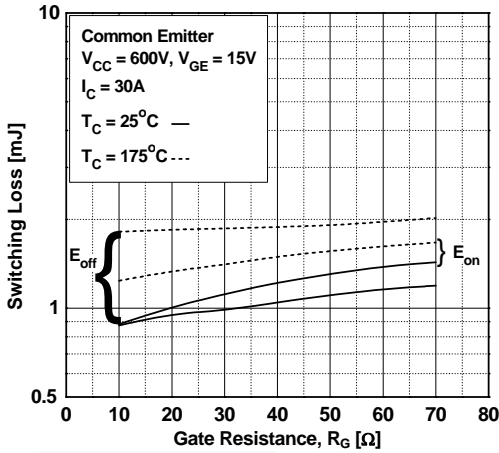


Figure 16. Switching Loss VS. Collector Current

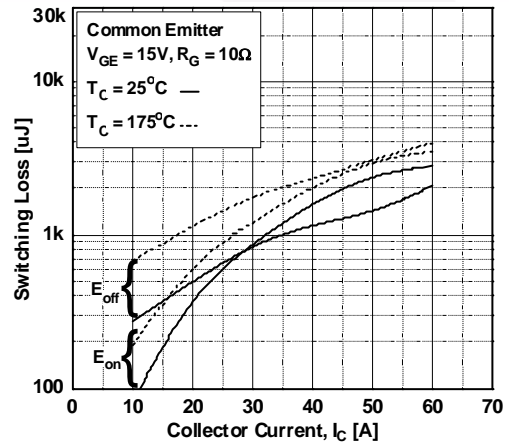


Figure 17. Turn off Switching SOA Characteristics

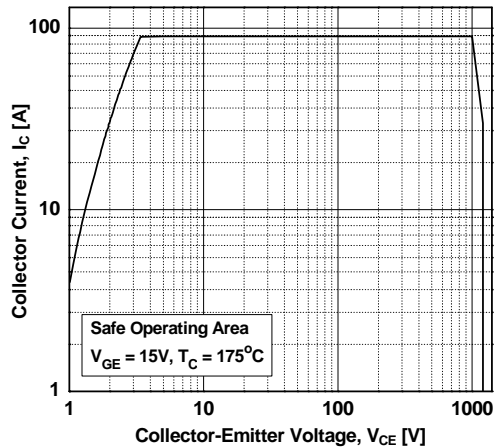


Figure 18. Forward Characteristics

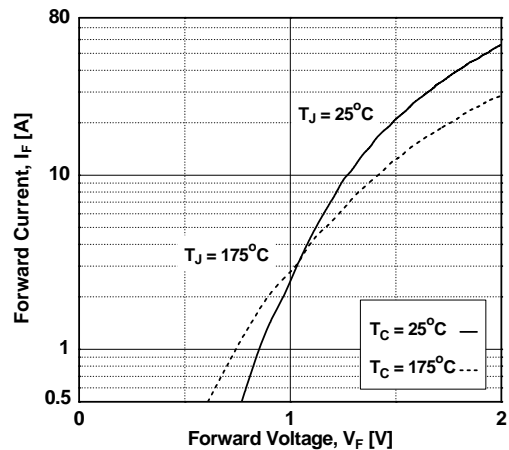
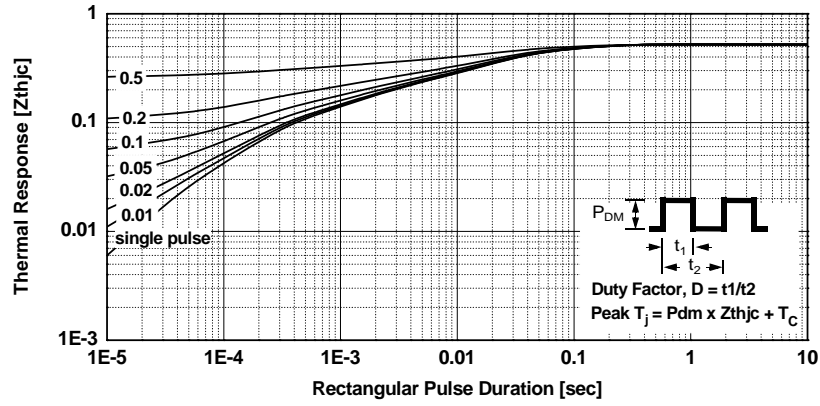
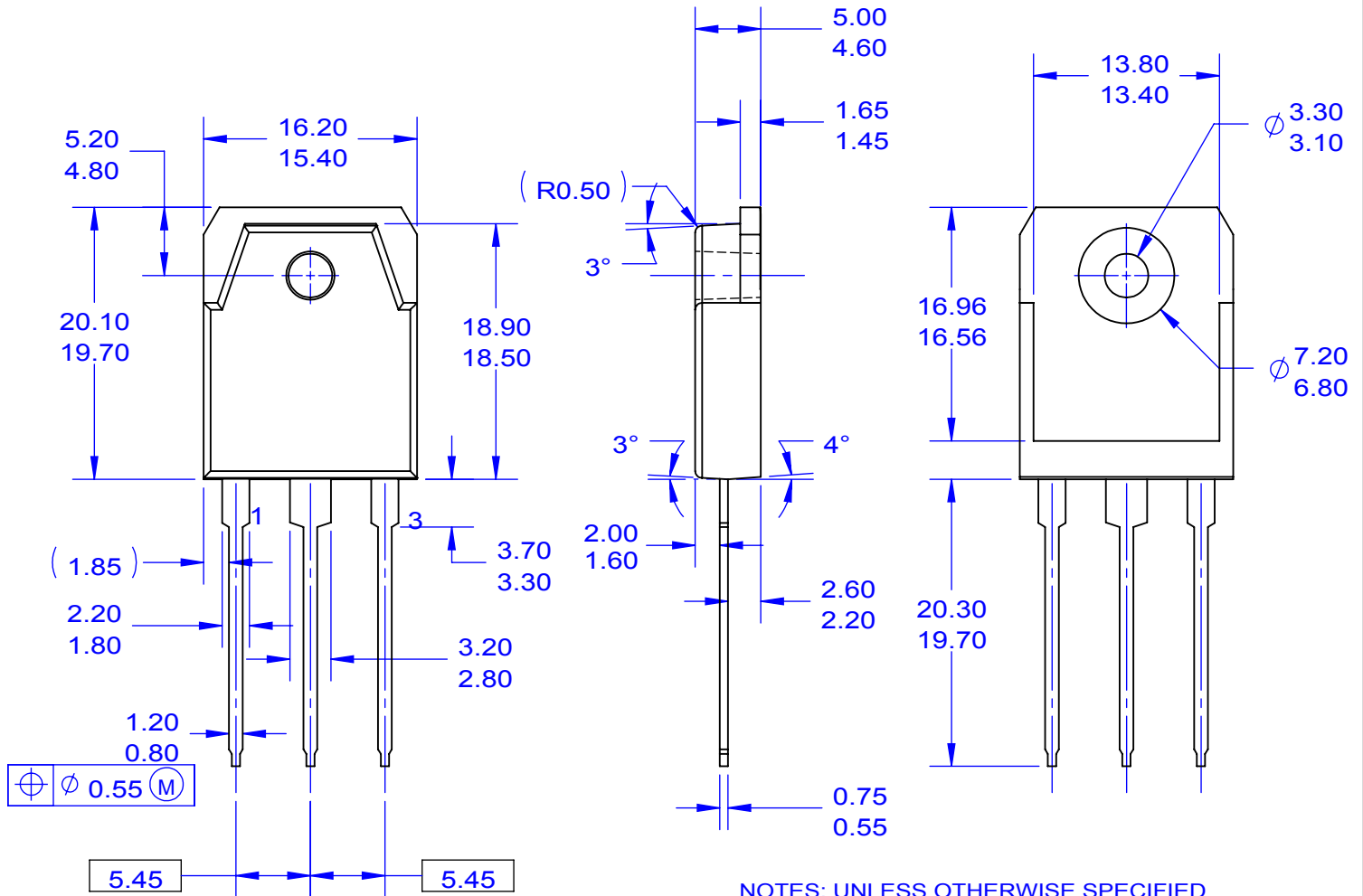


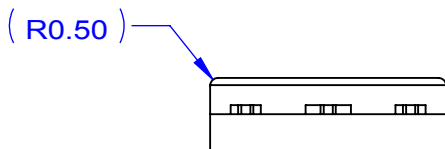
Figure 19. Transient Thermal Impedance of IGBT





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